

IN THE CLAIMS

1-35 (canceled)

36. (previously presented) A mixture comprising:

at least one substance A in the form of electrically conductive hard particle having a Mohs hardness of at least 5.5;

at least one substance B in the form of very soft or soft, inorganic, electrically conductive or semiconducting particle which are capable of sliding,

at least one substance C in the form of a metallic, soft or hard, electrically conductive or semiconducting particle or carbon black;

at least one binder; and

at least one of a crosslinking agent or a photoinitiator, one additive, one corrosion protection pigment D, one corrosion inhibitor which is not present in particle form; and at least one of an organic solvent or water,

wherein A, B and C are water-insoluble or sparingly water-soluble pigments, wherein the sum of the weight contents of the at least one substance B and the at least one substance C makes up 0.25 to 99.5 % of the weight content of the water-insoluble or sparingly water-soluble pigmentation $\Sigma (A + B + C)$, and the particle size substance A, based on the particle size transfer value d_{99} , measured with a Mastersizer of type S from Malvern Instruments, is less than 10 μm , and wherein said $\Sigma (A + B + C)$ relative to the sum of the total pigmentation $\Sigma (A + B + C + D)$ is 30wt.%.

Claims 37 - 70 (canceled)

71. (previously presented) A mixture according to claim 36, wherein the mixture of all the types of electrically conductive hard particles A has an average particle size d_{50} of from 0.1 to 2.5 microns.

72. (previously presented) A mixture according to claim 36, wherein the mixture of all the types of electrically conductive hard particles A has an average particle size d_{50} of from 0.2 to 2 microns.

73. (previously presented) A mixture according to claim 36, wherein the mixture of all the types of electrically conductive hard particles A has an average particle size d_{50} of from 0.2 to 2.5 microns.

74. (canceled)

75. (previously presented) A process comprising applying the mixture of claim 71 to a substrate.

76. (previously presented) A process comprising applying the mixture of claim 72 to a substrate.

77. (previously presented) A process comprising applying the mixture of claim 73 to a substrate.

78. (canceled)

79. (previously presented) A process comprising applying the mixture of claim 36 to a substrate.

80. (canceled)